MAXIMUM RATINGS

Symbol	Characteristics	Value	Unit
V _{CC}	DC Supply Voltage	-0.5 to +7.0	V
V _{IN}	DC Input Voltage	-0.5 to +7.0	V
V _{OUT}	DC Output Voltage $V_{CC} = 0$ High or Low State	-0.5 to 7.0 -0.5 to V _{CC} + 0.5	V
I _{IK}	Input Diode Current	-20	mA
lok	Output Diode Current $V_{OUT} < GND; V_{OUT} > V_{CC}$	+20	mA
I _{OUT}	DC Output Current, per Pin	+25	mA
I _{CC}	DC Supply Current, V _{CC} and GND	+50	mA
P _D	Power Dissipation in Still Air SC–88A, TSOP–5	200	mW
$\theta_{\sf JA}$	Thermal Resistance SC-88A, TSOP-5	333	°C/W
TL	Lead Temperature, 1 mm from Case for 10 secs	260	°C
TJ	Junction Temperature Under Bias	+150	°C
T _{stg}	Storage Temperature	-65 to +150	°C
V _{ESD}	ESD Withstand Voltage Human Body Model (Note 1) Machine Model (Note 2) Charged Device Model (Note 3)	> 2000 > 200 N/A	V
I _{Latchup}	Latchup Performance Above V _{CC} and Below GND at 125°C (Note 4)	±500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. Tested to EIA/JESD22-A114-A
- 2. Tested to EIA/JESD22-A115-A
- 3. Tested to JESD22-C101-A
- 4. Tested to EIA/JESD78

RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics	Min	Max	Unit
V _{CC}	DC Supply Voltage	3.0	5.5	V
V_{IN}	DC Input Voltage	0.0	5.5	V
V _{OUT}	DC Output Voltage $V_{CC} = 0$ High or Low State	0.0 0.0	5.5 V _{CC}	V
T _A	Operating Temperature Range	- 55	+125	°C
t _r , t _f	Input Rise and Fall Time $ \begin{array}{c} V_{CC} = 3.3 \ V \pm 0.3 \ V \\ V_{CC} = 5.0 \ V \pm 0.5 \ V \\ \end{array} $	- -	No Limit No Limit	ns/V

Device Junction Temperature versus Time to 0.1% Bond Failures

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

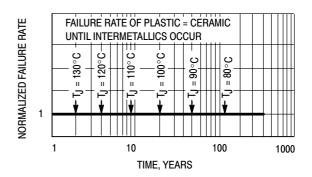


Figure 3. Failure Rate vs. Time Junction Temperature

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	T _A = 25°C		$T_A = 25^{\circ}C$ $T_A \le 85^{\circ}C$		85°C	C -55 ≤ T _A ≤ 125°C		
Symbol	Parameter	Test Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{T+}	Positive Threshold Voltage		3.0 4.5 5.5	1.20 1.58 1.79	1.40 1.74 1.94	1.60 2.00 2.10		1.6 2.0 2.0		1.6 2.0 2.0	V
V _{T-}	Negative Threshold Voltage		3.0 4.5 5.5	0.35 0.5 0.6	0.76 1.01 1.13	0.93 1.18 1.29	0.35 0.5 0.6		0.35 0.5 0.6		V
V _H	Hysteresis Voltage		3.0 4.5 5.5	0.30 0.40 0.50	0.64 0.73 0.81	1.20 1.40 1.60	0.30 0.40 0.50	1.20 1.40 1.60	0.30 0.40 0.50	1.20 1.40 1.60	V
V _{OH}	Minimum High-Level Output Voltage	$V_{IN} \le V_T - Min$ $I_{OH} = -50 \ \mu A$	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5		1.9 2.9 4.4		1.9 2.9 4.4		V
		I _{OH} = -4 mA I _{OH} = -8 mA	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		V
V _{OL}	Maximum Low-Level Output Voltage	$V_{IN} \ge V_T + Max$ $I_{OL} = 50 \mu A$	2.0 3.0 4.5		0.0 0.0 0.0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
		I _{OL} = 4 mA I _{OL} = 8 mA	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	V
I _{IN}	Maximum Input Leakage Current	V _{IN} = 5.5 V or GND	0 to 5.5			±0.1		±1.0		±1.0	μΑ
Icc	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			1.0		20		40	μΑ
I _{CCT}	Quiescent Supply Current	Input: V _{IN} = 3.4 V	5.5			1.35		1.50		1.65	mA
I _{OPD}	Output Leakage Current	V _{OUT} = 5.5 V	0.0			0.5		5.0		10	μΑ

AC ELECTRICAL CHARACTERISTICS C_{load} = 50 pF, Input t_{r}/t_{f} = 3.0 ns

			Т	A = 25°	C	T _A ≤	85°C	-55 ≤ T _A	≤ 125°C	
Symbol	Parameter	Test Conditions	Min	Тур	Max	Min	Max	Min	Max	Unit
t _{PLH} , t _{PHL}	$\begin{array}{c} \text{Maximum Propagation} \\ \text{Delay, A to } \overline{Y} \end{array}$	$V_{CC} = 3.3 \pm 0.3 \text{ V}$ $C_L = 15 \text{ pF}$ $C_L = 50 \text{ pF}$		7.0 8.4	12.8 16.3	1.0 1.0	15.0 18.5	1.0 1.0	17.0 20.5	ns
		$V_{CC} = 5.0 \pm 0.5 \text{ V}$ $C_L = 15 \text{ pF}$ $C_L = 50 \text{ pF}$		4.5 5.8	8.6 10.6	1.0 1.0	10.0 12.0	1.0 1.0	11.5 13.5	
C _{IN}	Maximum Input Capacitance			5	10		10		10	pF

		Typical @ 25°C, V _{CC} = 5.0 V	
C_{PD}	Power Dissipation Capacitance (Note 5)	10	pF

^{5.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

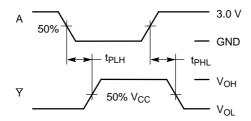
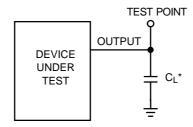


Figure 4. Switching Waveforms



*Includes all probe and jig capacitance

Figure 5. Test Circuit

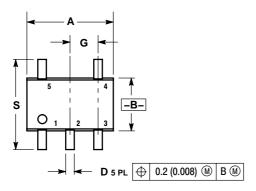
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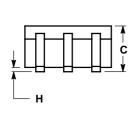
Device	Package	Shipping [†]
MC74VHC1GT14DFT1	SC70-5/SC-88A/SOT-353	
M74VHC1GT14DFT1G	SC70-5/SC-88A/SOT-353 (Pb-Free)	
MC74VHC1GT14DFT2	SC70-5/SC-88A/SOT-353	
M74VHC1GT14DFT2G	SC70-5/SC-88A/SOT-353 (Pb-Free)	3000/Tape & Reel
MC74VHC1GT14DTT1	SOT23-5/TSOP-5/SC59-5	
M74VHC1GT14DTT1G	SOT23-5/TSOP-5/SC59-5 (Pb-Free)	

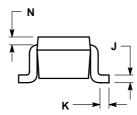
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SC-88A, SOT-353, SC-70 CASE 419A-02 **ISSUE J**



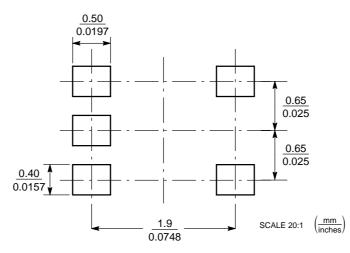




- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.
 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65	BSC
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20	REF
S	0.079	0.087	2.00	2.20

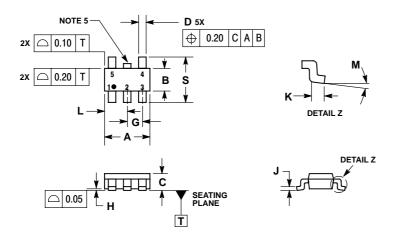
SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSOP-5 CASE 483-02 ISSUE G



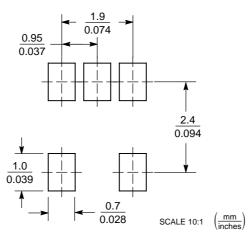
NOTES:

- DIMENSIONING AND TOLERANCING PER
 ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
- CONTROLLING DIMENSION: MILLIMETERS
 MAXIMUM LEAD THICKNESS INCLUDES
 LEAD FINISH THICKNESS. MINIMUM LEAD
 THICKNESS IS THE MINIMUM THICKNESS
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
- 5. OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

	MILLIMETERS				
DIM	MIN	MAX			
Α	3.00	BSC			
В	1.50	BSC			
С	0.90	1.10			
D	0.25	0.50			
G	0.95	BSC			
Н	0.01	0.10			
J	0.10	0.26			
K	0.20	0.60			
L	1.25	1.55			
М	0 °	10°			
S	2.50	3.00			

OF BASE MATERIAL

SOLDERING FOOTPRINT*



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